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PMIC N/A STANDARDIZED MILITARY DRAWING					PREPARED BY Konnett Rici CHECKED BY LEMANUS Seusing APPROVED BY					MICI 16K	ROCI	FENS IRCU:	DA ITS,	ME	N, OI 40RY	+IO 4	IGIT	AL,	CMOS							
THIS DRAWING IS AVAILABLE 'FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE				TS	DRAWING APPROVAL DATA 12 DECEMBER 1989 REVISION LEVEL				1	SIZE	SHE	(CAGE				59	62	-89	96	92					
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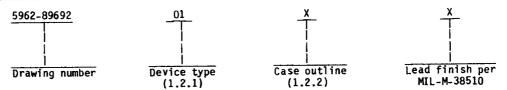
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DISTRIBUTION STATEMENT A. Approved for public release; distribution is unlimited.

1. SCOPE

1.1 Scope. This drawing describes device requirements for class B microcircuits in accordance with 1.2.1 of MIL-STD-883, "Provisions for the use of MIL-STD-883 in conjunction with compliant non-JAN devices".

1.2 Part number. The complete part number shall be as shown in the following example:



1.2.1 Device types. The device types shall identify the circuit function as follows:

Device type	Generic number	Circuit function	Access time
01	See 6.6	16K x 4 static ram	25 ns (data retention)
02	10	n	25 ns
03	n	н	20 ns (data retention)
04	16	40	20 ns
05		Ħ	15 ns (data retention)
06	ıı	11	15 ns

1.2.2 Case outlines. The case outlines shall be as designated in appendix C of MIL-M-38510, and as follows:

Outline letter	Case outline
K	F-6 (24-lead, .640" X .420" X .090"), flat package
X	Figure 1 (22-lead, 1.260" X .310" X .150"), dual-in-line package
Y	Figure 1 (22-lead, 1.110" X .310" X .175"), dual-in-line package
Z	Figure 1 (22-terminal, .490" X .290" X .080"), leadless chip carrier package

1.3 Absolute maximum ratings.

1/ All voltages referenced to V_{SS} . 2/ When a thermal resistance value is included in MIL-M-38510, appendix C, it shall supersede the value stated herein.

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1.4 Recommended operating conditions.			
Supply voltage (V_{CC}) Ground voltage (V_{SS}) Input high voltage (V_{IH}) Input low voltage (V_{IL}) Operating case temperature range (T_C)		0 Y dc +2.2 Y dc to Y _{CC} +0.5 Y dc 0.5 Y dc to .8 Y dc 4/	
2. APPLICABLE DOCUMENTS			
2.1 Government specification, standard, specification, standard, and bulletin of the Index of Specifications and Standards specified herein.	ne issue l	etin. Unless otherwise specified, the fol listed in that issue of the Department of the solicitation, form a part of this draw	Defense
SPECIFICATION			
MILITARY			
MIL-M-38510 - Microcircui	ts, Gener	ral Specification for.	
STANDARD			
MILITARY			
MIL-STD-883 - Test Method	is and Pro	ocedures for Microelectronics.	
BULLETIN			
MILITARY			
MIL-BUL-103 - List of Sta	andardized	d Military Drawings (SMD's).	
(Copies of the specification, standard, a specific acquisition functions should be ol contracting activity.)		tin required by manufacturers in connectio rom the contracting activity or as directe	
2.2 Order of precedence. In the event of references cited herein, the text of this of	of a confi irawing si	lict between the text of this drawing and hall take precedence.	the
3. REQUIREMENTS			
3.1 <u>Item requirements</u> . The individual in MIL-STD-883, "Provisions for the use of MIL and as specified herein.		irements shall be in accordance with 1.2.1 in conjunction with compliant non-JAN dev	
3.2 Design, construction, and physical of dimensions shall be as specified in MIL-M-3	dimensions 38510 and	s. The design, construction, and physical Therein.	
3.2.1 <u>Terminal connections</u> . The termina	al connect	tions shall be as specified on figure 2.	
3.2.2 <u>Truth table</u> . The truth table sha	ll be as :	specified on figure 3.	
3.2.3 <u>Case outlines</u> . The case outlines	shall be	in accordance with 1.2.2 herein.	
3/ All voltages referenced to V _{SS} . 4/ V _{IL} negative undershoots to a minimum width.	n of -2.0	V dc are allowed with a maximum 20 ns pul	se
STANDARDIZED	SIZE		
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- 3.2.4 Die overcoat. Polyimide and silicone coatings are allowable as an overcoat on the die for alpha particle protection provided that each coated microcircuit inspection lot (reference MIL-M-38510, 3.1.3.8) shall be subjected to and pass the internal moisture content test (test method 1018 of MIL-STD-883). The frequency of the internal water vapor testing may not be decreased unless approved by the preparing activity.
- 3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full case operating temperature range.
- 3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are described in table I.
- $3.5\,$ Marking. Marking shall be in accordance with MIL-STD-883 (see $3.1\,$ herein). The part shall be marked with the part number listed in $1.2\,$ herein. In addition, the manufacturer's part number may also be marked as listed in MIL-BUL-103 (see $6.6\,$ herein).
- 3.6 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-BUL-103 (see 6.6 herein). The certificate of compliance submitted to DESC-ECS prior to listing as an approved source of supply shall affirm that the manufacturer's product meets the requirements of MIL-STD-883 (see 3.1 herein) and the requirements herein.
- 3.7 Certificate of conformance. A certificate of conformance as required in MIL-STD-883 (see 3.1 herein) shall be provided with each lot of microcircuits delivered to this drawing.
- 3.8 Verification and review. DESC, DESC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.
 - 4. QUALITY ASSURANCE PROVISIONS
- 4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with section 4 of MIL-M-38510 to the extent specified in MIL-STD-883 (see 3.1 herein).
- 4.2 Screening. Screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection. The following additional criteria shall apply:
 - a. Burn-in test, method 1015 of MIL-STD-883.
 - (1) Test condition D using the circuit submitted with the certificate of compliance (see 3.6 herein).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.
- 4.3 Quality conformance inspection. Quality conformance inspection shall be in accordance with method 5005 of MIL-STD-883 including groups A, B, C, and D inspections. The following additional criteria shall apply.

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	1	ABLE I. Electr	ical perform	ance cha	racteristic	<u>s</u> .			
Test	Symbol	Cond	litions		Group A	Device	Limits		Unit
	 	-55°C < T V _{SS} = 0 V, 4 unless oth	C < +125°C .5 V < V _{CC <} erwise speci	5.5 V fied	subgroups 	types	Min	Max	
Input leakage current	ILI	V _{CC} = max, V _{IN}	= GND to V _C (1,2,3	A11		10	μA
Output leakage current	ILO	VCC = max, VOUT = GND to V CE > VIH, WE			1,2,3	All		10 	 μ Α
Output low voltage	V _{OL}	V _{CC} = 4.5 V, I ₀ V _{IL} = 0.8 V, V _I	L = 8 mA, H = 2.2 V		1,2,3	All		0.4	 V
Output high voltage	V _{OH}		H = -4 mA, H = 2.2 V		1,2,3	All	2.4	 	V
	 			· · · · · · · · · · · · · · · · · ·		01,03		120	<u> </u>
Operating supply current	I _{CC1}	CE = V _{IL} , outpu V _{CC} = max, f =	ts open, ^{1/t} AVAX		1,2,3	02,04		130	mA
	 	 				05,06		150	
Standby power supply current	I _{CC2}		its open,		1,2,3	01,03,05	j 1	20	mA
(TTL)	<u>i</u>	1			<u> </u>	02,04,06	<u> </u>	50	<u> </u>
Standby power supply current	I _{CC3}	V_{CC} +0.2 V $\geq \overline{CE}$ outputs open,			1,2,3	01,03,05	<u> </u>	5	mA
(CMOS)] 		N > VCC -0.7 ≥ -0.2 V,	2 V	<u> </u> 	02,04,06		20^).	
Data retention current	I _{CC4}		V _{CC} =	V PR	1,2,3	01,03,05,	\ 	600	μA
Input capacitance	C _{IN} 1/	$ V_I = 0 V$ $ f = 1 MHz, T_A = 1$ see 4.3.1c	+25°C,		4	A11 		10	l pF l
Output capacitance	C _{OUT} 1/	$ V_0 = 0 V$ $ f = 1 MHz, T_A = 1$ see 4.3.1c	+25°C,		4	All	 	10	pF
See footnotes at	end of ta	ble.							
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	TABLE I	. Electrical pe	rformance	character	istics - Co	ntinued.			
Test	Symbol	Cond	itions	2/	Group A	Device	Lim	its	 Unit
	 	-55°C < To V _{SS} = 0 V, 4. unless other	itions < +125°C 5 V < V _{CC} erwise spe	_ ≤ 5.5 V ≎Tfied	subgroups 	types	Min	Max	[
Read cycle time	tavax	See figure 4			9,10,11	01,02	25		ns
	1	 				03,04	20	! 	<u> </u>
	1	 				05,06	15		.
Address cycle	tavov				9,10,11	01,02		25	<u> </u>
time	*** *	<u> </u>			1	03 ,04	} 	l 20_	<u> </u>
	[]] 				05,06	 	l 15	<u> </u>
Chip enable	t _{ELQV}	Ī			9,10,11	01,02		25	<u> </u>
access time		 				03,04		l 20	<u> </u>
	1	1				05,06		15	<u> </u>
Output hold	tAVQX				9,10,11	01-04	3		<u> </u>
from address change		! !			i 	05,06	2	<u> </u>	1
Chip select to	t _{ELQX}	Ţ			9,10,11	01-04	3	<u> </u>	<u> </u>
output in low Z	1/ 3/	 			<u> </u>	05,06	2		<u> </u>
Chip select to output in high Z	t _{EHQZ} 1/3/				9,10,11	 A11 		15	
Write enable to output in high	t _{WLQZ}	† !			9,10,11	01,02		15	† - -
Z		 				03,04		12	<u> </u>
	 	· · · · · · · · · · · · · · · · · · ·				05,06]	10	
Data valid to end of write	t _{DV WH}	Ť Į			9,10,11	01,02	15		<u> </u>
		; 				03,04	1 12		T
		- - - - -				05,06	10		T I
See footnotes at	end of ta	ible.							
	DARDIZ		SIZE A				5962-89	692	
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	TABLE I	. Electrical po	erformance	characte	ristics - Co	ntinued.			
Test	Test Symbol -55°C				Group A subgroups	Device types	Lim	its	Unit
		-55°C < T V _{SS} = 0 V, 4 unless oth	.57 < V _{CC} erwise spe	< 5.5 V cffied		l cypes	Min	Max	
Data hold time	t _{WHDX}	 See figure 4 			9,10,11	 All 	0	! 	ns
Output active from end of write	t _{WHQV} 1/3/	 			9,10,11	A11	3		
Write cycle time	tavav				9,10,11	01,02	25	 	<u> </u>
	 					03,04	 20 		
	 				· .	 05,06 	15	 	
Chip select to end of write	t _{ELWH}	 			9,10,11	01,02	20		-
	 					03,04	17	[
	i 	 			·	05,06	14	[] !	T
Address valid to end of write	t _{AVWH}	<u> </u>			9,10,11	01,02	20		Ţ
	i ! !					03,04	17	! 	T
					·	05,06	14	<u> </u>	Ť
Address setup	t _{AVML}				9,10,11	A11	0]]]	T
Write pulse width	twLwH	Г і І			9,10,11	01,02	20] 	T
	 					03,04	17	 	T
	j 1	 				05,06	14		Ť !
See footnotes at	end of ta	ble.						•	
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	TABLE	I. Electrical performance character	ristics - Co	ntinued.			
Test	Symbol	Conditions 2/	Group A	Device	Lim	its	Unit
	 	Conditions $\frac{2}{}$ -55°C < T _C < +125°C V _{SS} = 0 V, 4.5 V < V _{CC} < 5.5 V unless otherwise specified	subgroup s	types	Min	Max	
Write recovery time	t _{EHAX}	See figure 4	9,10,11	01-04	5		ns
				05-06	3		

1/ This parameter tested intially and after any design or process change which could affect this parameter, and is therefore guaranteed to the limits specified in table I.

2/ AC parameters are tested using input rise and fall times of 5 ns and input pulse levels of GND to 3.0 V. Both input and output timing reference levels are 1.5 V, and the output load is shown on figure 5.

3/ Transition is measured ±500 mV from steady state.

4.3.1 Group A inspection.

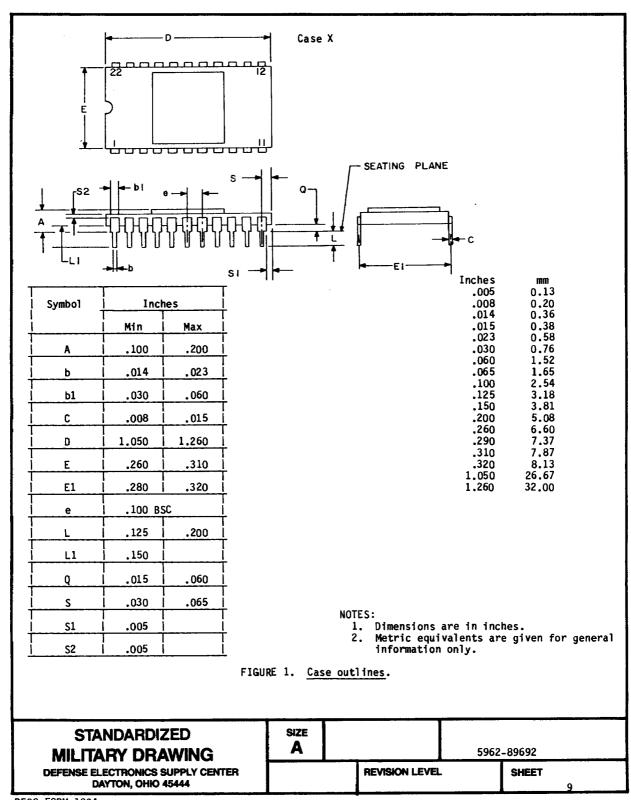
- a. Tests shall be as specified in table II herein.
- b. Subgroups 5 and 6 in table I, method 5005 of MIL-STD-883 shall be omitted.
- c. Subgroup 4 (C_{IN} and C_{OUT} measurements) shall be measured for the initial characterization and after any process or design changes which may affect capacitance. Sample size is 15 devices with no failures, and all input and output terminals tested.
- d. Subgroups 7 and 8 tests sufficient to verify the truth tables.

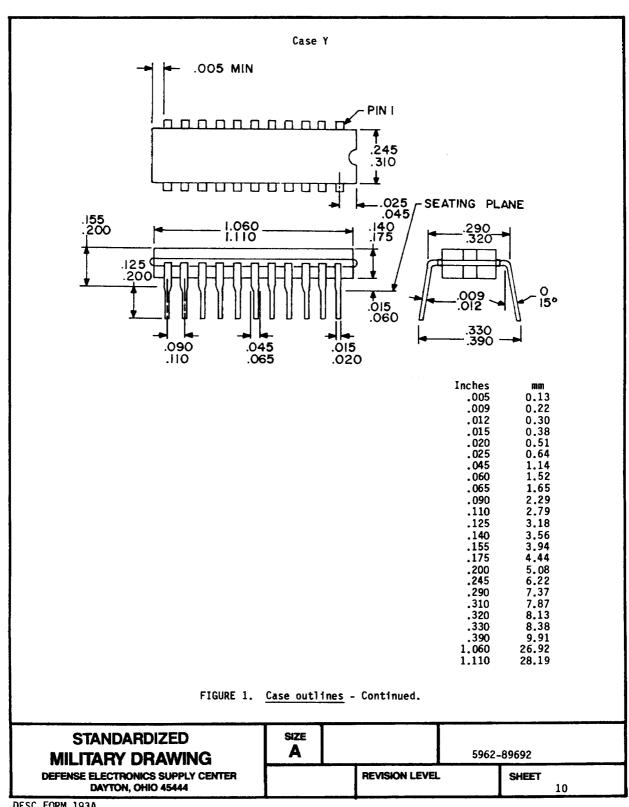
4.3.2 Groups C and D inspections.

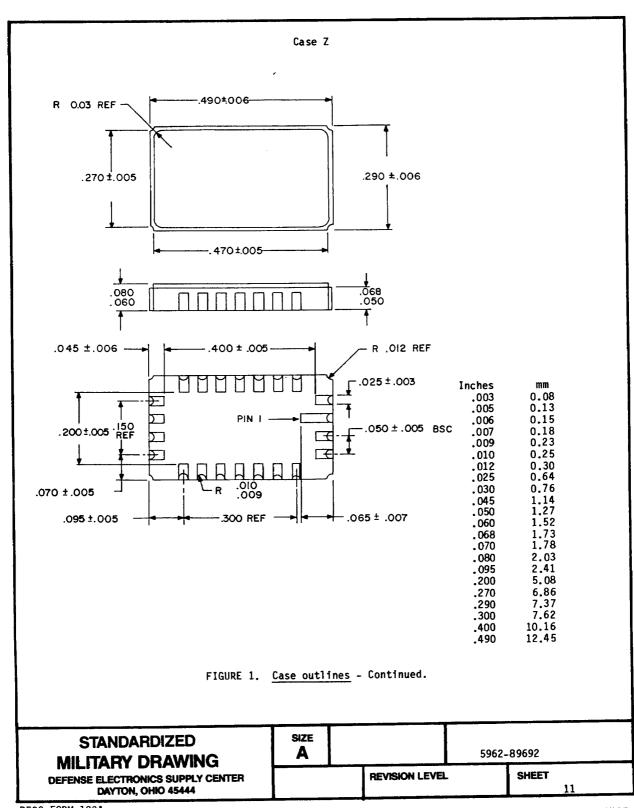
- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test conditions; method 1005 of MIL-STD-883:
 - (1) Test condition D using the circuit submitted with the certificate of compliance (see $3.6 \ \text{herein}$).
 - (2) $T_A = +125^{\circ}C$, minimum.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

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Device types 01 through 06 Case outlines X, Y, and ZTerminal number Terminal symbol 1 **A**5 A₀ 2 **A**6 A₁ 3 A2 **A**7 4 A۶ Aз 5 A9 **A**4 6 A₁₀ **A**5 7 A₁₁ **A**6 8 A₁₂ **A**7 9 A₁₃ 8 10 CE CE 11 GND NC 12 WE GND 1/00 WE 13 14 I/0₁ 1/01 15 1/02 I/02 16 1/03 1/03 17 I/04 A₀ 18 NC **A**₁ 19 A9 A2 20 Аз A₁₀ 21 A4 A₁₁ 22 VCC A12 23 A₁₃ 24 VCC

NC = no connection

FIGURE 1. Terminal connections.

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Device types 01 through 06	Device	types	01	through	06
----------------------------	--------	-------	----	---------	----

CE	WE	Mode	I/0	Power	
H	i X	 Not selected	High Z	 Standby	
Ĺ	L	Write	DIN	Active	
i L	Н 1	Read 	D _{OUT}	Active	

H = Logic "1" state
L = Logic "0" state
X = Don't care

FIGURE 3. Truth table.

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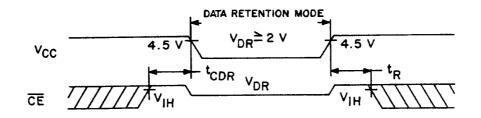
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Low $V_{\mbox{\footnotesize{CC}}}$ data retention waveform

(Device types 01, 03, and 05)



NOTE: $t_{CDR} = 0$ ns (minimum); may not be tested, but is guaranteed. $t_r = t_{AVAX}$

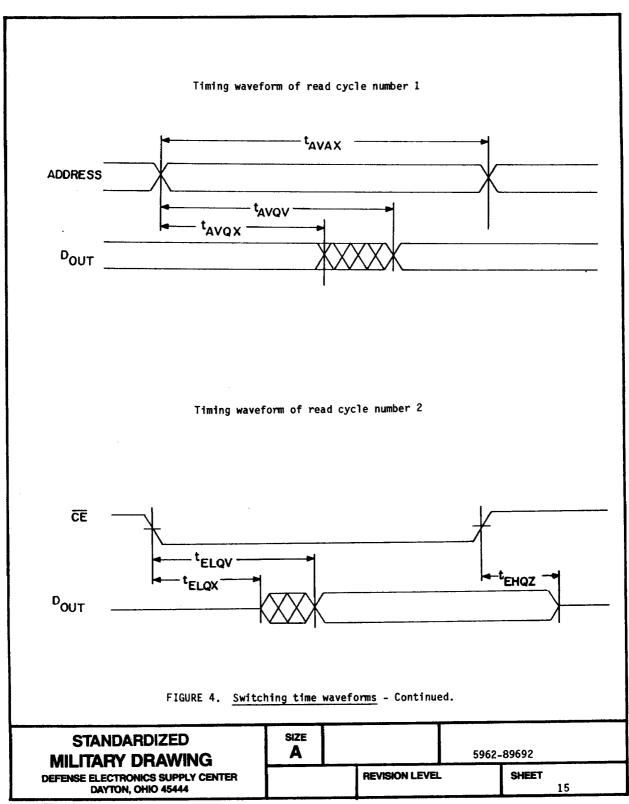
FIGURE 4. Switching time waveforms.

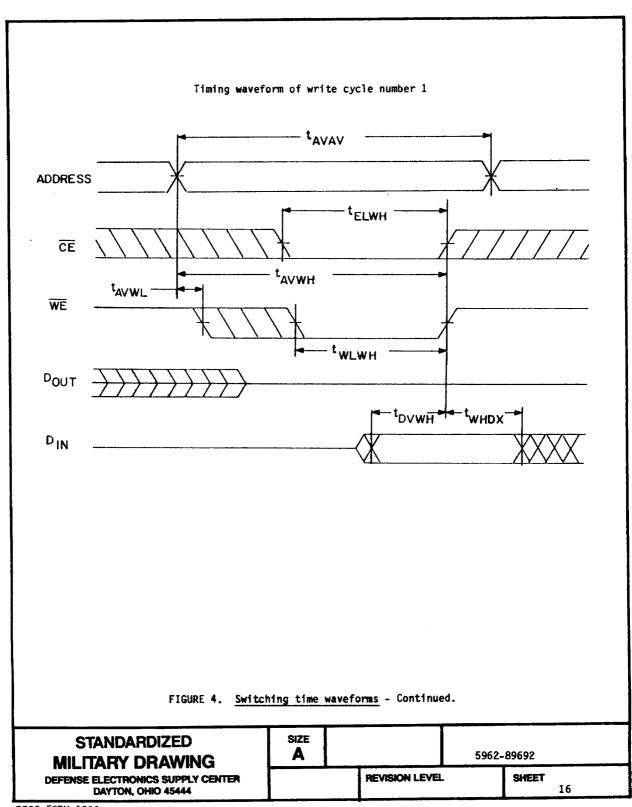
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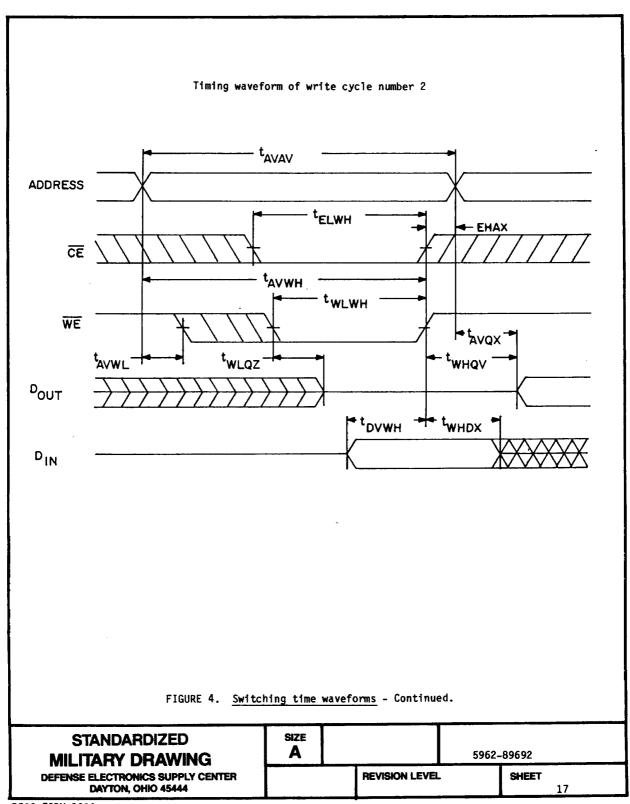
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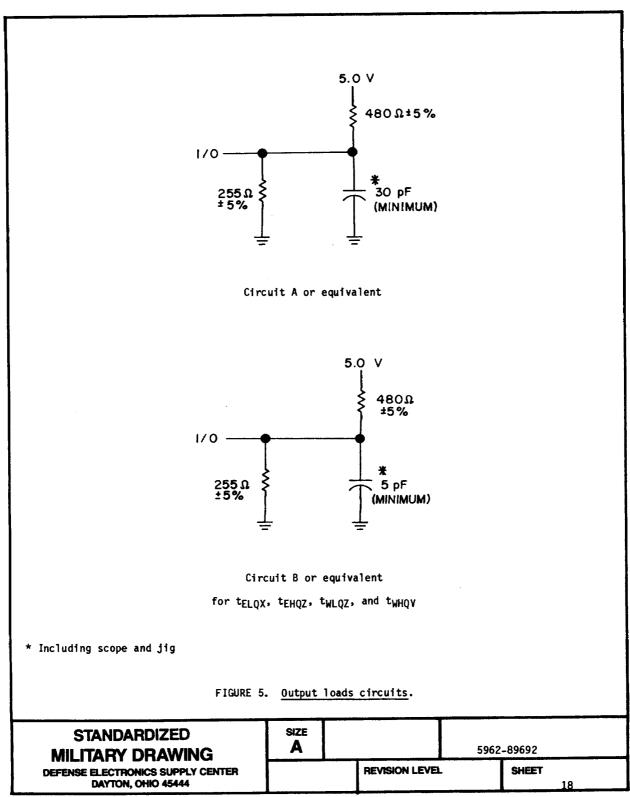
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IABLE II. Electrical test requirements	.•
MIL-STD-883 test requirements	Subgroups (per method 5005, table I)
Interim electrical parameters (method 5004)	
Final electrical test parameters (method 5004)	1*,2,3,7*,8A, 8B,9,10,11
Group A test requirements (method 5005)	1,2,3,4**,7***, (8A,8B)***,9,10,11
Groups C and D end-point electrical (method 5005)	2,3,7,8A,8B

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5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-M-38510.

6. NOTES

- 6.1 Intended use. Microcircuits conforming to this drawing are intended for use when military specifications do not exist and qualified military devices that will perform the required function are not available for OEM application. When a military specification exists and the product covered by this drawing has been qualified for listing on QPL-38510, the device specified herein will be inactivated and will not be used for new design. The QPL-38510 product shall be the preferred item for all applications.
- 6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.
- 6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished in accordance with MIL-STD-481 using DD Form 1693, Engineering Change Proposal (Short Form).
- 6.4 Record of users. Military and industrial users shall inform Defense Electronics Supply Center when a system application requires configuration control and the applicable SMD. DESC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronics devices (FSC 5962) should contact DESC-ECS, telephone 513-296-6022.
- 6.5 Comments. Comments on this drawing should be directed to DESC-ECS, Dayton, Ohio 45444, or telephone 513-296-5375.

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^{*} PDA applies to subgroups 1 and 7

^{**} See 4.3.1c.

^{***} See 4.3.1d.

6.6 Approved sources of supply. Approved sources of supply are listed in MIL-BUL-103. Additional sources will be added to MIL-BUL-103 as they become available. The vendors listed in MIL-BUL-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DESC-ECS. The approved sources of supply listed below are for information purposes only and are current only to the date of the last action of this document.

Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1</u> /	Replacement military specification part number
5962-8969201KX	61772	IDT7188L25EB	
5962-8969201XX	75569	P4C188L-25CMB	
5962-8969201YX	61772	IDT7188L-25DB	
5962-8969201ZX /	75569	 P4C188L-25LMB 	
5962-8969202KX	65786 61772	CY7C164A-25KMB IDT7188S25EB	
5962-8969202XX	6Y440 75569	 MT5C6404C-25883C P4C188-25CMB	·
5962-8969202YX	61772 65786	IDT7188S25DB CY7C164A-25DMB	
5962-89692027X /	75569 67440 65786	P4C188-25LMB MT5C6404EC-25883C CY7C164A-25LMB	
5962-8969203KX /	61772	IDT7188L20EB	
 5962-8969203YX /	61772	IDT7188L200B	
 5962-8969204KX 	65786	CY7C164A-20KMB IDT7188S20EB	
5962-896920 4 XX	6Y440 75569	MT5C6404C-20883C P4C188-20CMB	

See footnote at end of table.

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Military drawing part number	Vendor CAGE number	Vendor similar part number <u>1</u> /	Replacement military specification part number
5962-8969204YX /	61772	 IDT7188S2ODB CY7C164A-2ODMB	
5962-8969204ZX /	75569 64440 65786	P4C188-20LMB P4C188-20LMB MT5C6404EC-20883C CY7C164A-20LMB	
5962-8969205KX /	61772	IDT7188L15EB	
5962-8969205YX /	61772	IDT7188L15DB	
5962-8969206KX /	61772	I IDT7188-20EB	
5962-8969206XX /	6Y440 75569	MT5C6404C-15883C P4C188-15CMB	
5962-8969206ZX /	6Y440 75569	MT5C6404EC-15883C P4C188-15LMB	

 $\frac{1}{2}$ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE number	Vendor name and address
6Y44O	Micron Technology 2805 E. Columbia Road Boise, ID 83706
61772	Integrated Device Technology, Incorporated 1566 Moffett Boulevard Salinas, CA 93905 Point of contact: 3236 Scott Boulevard Santa Clara, CA 95054
65786	Cypress Semiconductor 3901 N. First Street San Jose, CA 95134
75569	Performance Semiconductor Corporation 610 East Weddell Drive Sunnyvale, CA 94089

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